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Serial No. 10/045,653  
Attorney Docket No. 40025.002

#4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:  
Michael Vyvoda, et al.

Serial No.: 10/045,653

Filed: November 7, 2001

For: **Metal Structures for Integrated  
Circuits and Methods for Making the Same**

Confirmation No. 9868

Group Art Unit: 2812

Examiner: Unassigned

Box Missing Parts  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

**PRELIMINARY AMENDMENT**

Prior to examination of this application on the merits, Applicants respectfully request entry of the following amendment.

**IN THE CLAIMS**

Please add the following claims.

--10. The method of claim 9, wherein a portion of the metal structure has a dimension greater than about 1 micron.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D. C. 20231, on this 19<sup>th</sup>  
day of June 2002.

Signed: Emily J. Foley  
Dated: 6/19/02

11. The method of claim 10, wherein a portion of the metal structure has a dimension less than about 0.25 micron.

12. A method for making a semiconductor device, comprising:  
providing a metal structure on a substrate, the metal structure comprising tungsten and a portion of the metal structure having a dimension greater than about 1 micron; and  
providing an insulating layer over the metal structure;  
providing a capping structure over the insulating layer; and  
annealing the resulting structure;  
wherein the capping structure and annealing decreases peeling of the metal structure when heated.

13. A method for making a semiconductor device, comprising:  
providing a metal structure on a substrate, the metal structure comprising tungsten and a portion of the metal structure having a dimension greater than about 1 micron; and  
providing an insulating layer over the metal structure;  
providing a capping structure over the insulating layer; and  
annealing the resulting structure;  
wherein the annealing decreases peeling of the metal structure when heated.--

#### REMARKS

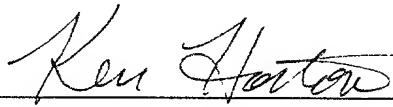
Applicants hereby submit this Preliminary Amendment in response to the Notice of Missing Parts (the "Notice"). The Notice noted that the Office had not received several items that were originally filed, including page 16 of the specification and the filing fee.

Applicants strongly disagree that these items were not part of the application as originally filed. These items were actually submitted as part of the application, but were separated from the application while being handled by the U.S. Postal Service at off-site storage because of anthrax considerations. Unfortunately, the postcard receipt was also lost during this handling procedure. Thus, Applicants were in a position of being unable to prove that page 16 of the specification was submitted as part of the original application.

For cost and other considerations, Applicants did not petition this issue. Instead, Applicants submit the information in page 16 of the specification via the present Preliminary Amendment. Looking at page 15 of the specification (containing claims 1-9) and page 17 of the specification (containing claims 14-18), it is obvious that page 16 of the specification contained claims 10-13. These same claims 10-13 are now submitted via this Preliminary Amendment.

If there is any fee due in connection with the filing of this Preliminary Amendment, including a fee for any extension of time not accounted for above, please charge the fee to our Deposit Account No. 18-0013.

Respectfully Submitted,

By   
KENNETH E. HORTON  
Reg. No. 39,481

Date: June 19, 2002